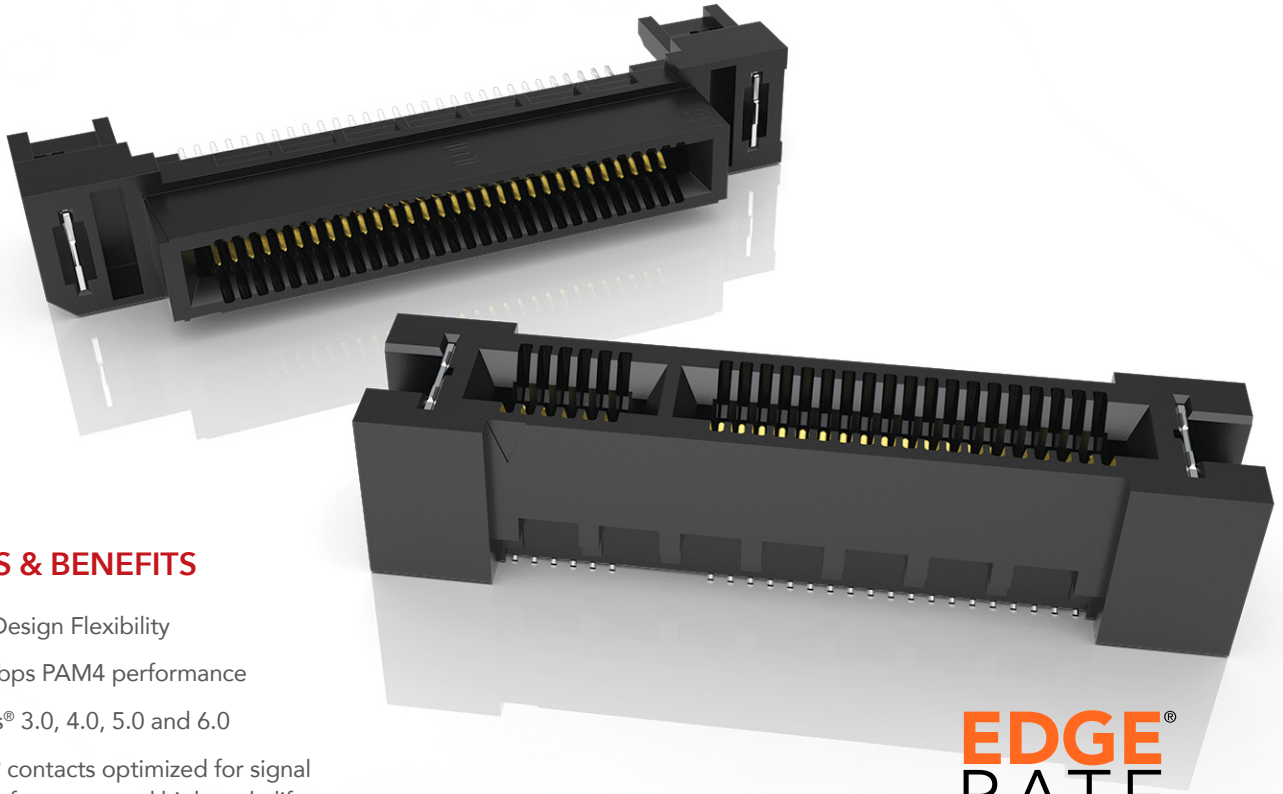


# GENERATE<sup>®</sup>

## HIGH-SPEED EDGE CARD SYSTEMS

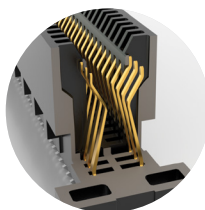
0.60 mm, 0.80 mm and 1.00 mm PITCH



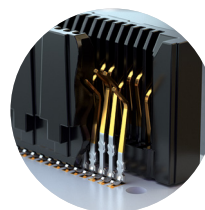
### FEATURES & BENEFITS

- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express<sup>®</sup> 3.0, 4.0, 5.0 and 6.0
- Edge Rate<sup>®</sup> contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available

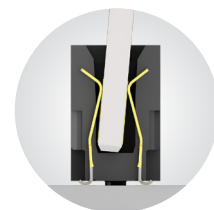
**EDGE  
RATE<sup>®</sup>**  
CONTACT



Rugged tucked beam technology (HTEC8)



Differential pair for increased speed (HSEC8-DP)



Custom designs allow for misalignment in the X-Y axes (HSEC1)

### KEY SPECIFICATIONS

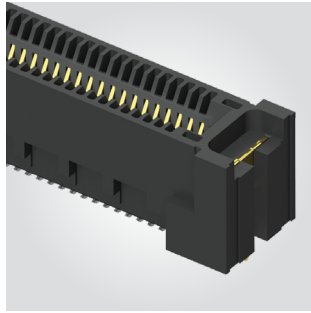
SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC	Yes
HSEC8	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC	Yes

**(0.80 mm) .0315" PITCH • RUGGED HIGH-SPEED EDGE CARD SOCKET**

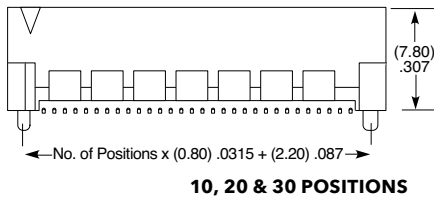
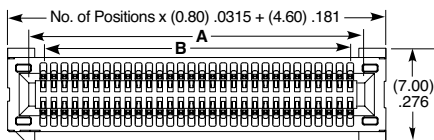
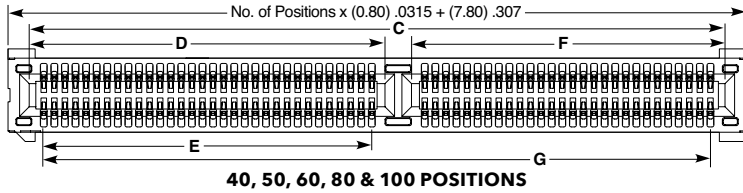
<b>HTEC8</b>	<b>1</b>	<b>POSITIONS PER ROW</b>	<b>01</b>	<b>PLATING OPTION</b>	<b>DV</b>	<b>OPTION</b>	<b>OTHER OPTION</b>	<b>"X"R</b>
		10, 20, 30, 40, 50, 60, 80, 100		<p><b>-L</b> = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on tail</p> <p><b>-S</b> = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tail</p>		<p>Leave blank for no alignment pin</p> <p><b>-A</b> = Alignment Pin</p> <p><b>-WT</b> = Weld Tab (-A option required)</p> <p><b>-BL</b> = Board Lock (-A option required) (Weld tab standard)</p>	<p><b>-K</b> = (7.00 mm) .276" DIA Polyimide Pick &amp; Place Pad</p>	<p>Leave blank for Tray Packaging</p> <p><b>-TR</b> = Tape &amp; Reel (10 thru 60 positions only)</p> <p><b>-FR</b> = Full Reel Tape &amp; Reel (must order max. quantity per reel; contact Samtec for quantity breaks) (10 thru 60 positions only)</p>

**HTEC8**

Card Mates:  
(1.60 mm) .062" thick card

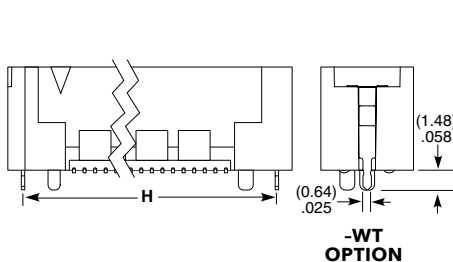


POSITIONS PER ROW	C	D	E	F	G
40	(36.60) 1.440	(18.90) .744	(16.80) .661	(15.70) .618	(34.40) 1.354
50	(44.60) 1.756	(22.90) .902	(20.80) .819	(19.70) .776	(42.40) 1.669
60	(52.60) 2.071	(26.90) 1.059	(24.80) .976	(23.70) .933	(50.40) 1.984
80	(68.60) 2.701	(26.90) 1.059	(24.80) .976	(39.70) 1.563	(66.40) 2.614
100	(84.60) 3.331	(26.90) 1.059	(24.80) .976	(55.70) 2.193	(82.40) 3.244



POSITIONS PER ROW	A	B
10	(9.40) .370	(7.20) .283
20	(17.40) .685	(15.20) 5.98
30	(25.40) 1.000	(23.20) .913

POSITIONS PER ROW	H
10	(14.90) .587
20	(22.90) .902
30	(30.90) 1.217
40	(42.10) 1.657
50	(50.10) 1.972
60	(58.10) 2.287
80	(74.10) 3.917
100	(90.10) 3.547



**Note:**  
Some sizes, styles and options are non-standard, non-returnable.

View complete specifications at: [samtec.com?HTEC8](http://samtec.com?HTEC8)